

ABSTRACT

To provide a retaining ring (10) for holding semiconductor wafers in a chemical mechanical polishing apparatus, which can be manufactured more cost-effectively than hitherto and, in particular, fitted more cost-effectively than hitherto with a new plastic part, it is proposed that the retaining ring (10) to be fitted on a chemical mechanical polishing apparatus for semiconductor wafers comprise: a carrier ring (12) made of a first material and having fitting elements for fitting the carrier ring (12) on the polishing apparatus; and a bearing ring made of a plastic material and arranged concentrically on the carrier ring, the bearing ring resting with a first front side on a polishing surface of the polishing apparatus and being held on its side axially opposed to the first front side releasably, non-rotatably, with a positive and/or frictional connection and without adhesive on the carrier ring (12), with the first material having a higher rigidity than the plastic material of the bearing ring.